



**12500 TI Boulevard, MS 8640, Dallas, Texas 75243**

**PCN#20240423000.2**

**Qualification of Cu as an alternate bond wire for select devices  
Change Notification / Sample Request**

**Date:** April 23, 2024

**To:** Mouser PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within **30 days** of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

Sincerely,

Change Management Team  
SC Business Services

**20240423000.2**  
**Change Notification / Sample Request**  
**Attachments**

**Products Affected:**

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

<b>DEVICE</b>	<b>CUSTOMER PART NUMBER</b>
TPS92691QPWPQ1	NULL
TPS92691QPWPRQ1	NULL
TPS92691QPWPTQ1	NULL
TPS92692QPWPRQ1	NULL
TPS92692QPWPTQ1	NULL

Technical details of this Product Change follow on the next page(s).

<b>PCN Number:</b>	PCN#20240423000.2			<b>PCN Date:</b>	April 23, 2024								
<b>Title:</b>	Qualification of Cu as an alternate bond wire for select devices												
<b>Customer Contact:</b>	Change Management Team		<b>Dept:</b>	Quality Services									
<b>Proposed 1<sup>st</sup> Ship Date:</b>	October 20, 2024		<b>Sample Requests accepted until:</b>	May 23, 2024*									
<b>*Sample requests received after May 23, 2024 will not be supported.</b>													
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Material								
<input checked="" type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Process								
<input checked="" type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input type="checkbox"/>	Wafer Fab Site								
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Wafer Fab Material								
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input type="checkbox"/>	Wafer Fab Process								
<b>PCN Details</b>													
<b>Description of Change:</b>													
<p>This PCN is to inform of an alternative bond wire qualification for the devices in the product affected section as follows:</p> <table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="background-color: #d9e1f2; text-align: center; padding: 5px;">What</th> <th style="background-color: #d9e1f2; text-align: center; padding: 5px;">Current</th> <th style="background-color: #d9e1f2; text-align: center; padding: 5px;">Additional</th> </tr> </thead> <tbody> <tr> <td style="text-align: center; padding: 5px;"><b>Bond wire type, Diameter</b></td> <td style="text-align: center; padding: 5px;"><b>Au, 0.96 mil</b></td> <td style="text-align: center; padding: 5px;"><b>Cu, 0.8 mil</b></td> </tr> </tbody> </table>						What	Current	Additional	<b>Bond wire type, Diameter</b>	<b>Au, 0.96 mil</b>	<b>Cu, 0.8 mil</b>		
What	Current	Additional											
<b>Bond wire type, Diameter</b>	<b>Au, 0.96 mil</b>	<b>Cu, 0.8 mil</b>											
<b>Reason for Change:</b>													
<p>Continuity of supply.</p> <ol style="list-style-type: none"> <li>1) To align with world technology trends and use wiring with enhanced mechanical and electrical properties</li> <li>2) Maximize flexibility within our Assembly/Test production sites.</li> <li>3) Cu is easier to obtain and stock</li> </ol>													
<b>Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):</b>													
None													
<b>Impact on Environmental Ratings</b>													
<p>Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.</p> <table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="background-color: #d9e1f2; text-align: center; padding: 5px;">RoHS</th> <th style="background-color: #d9e1f2; text-align: center; padding: 5px;">REACH</th> <th style="background-color: #d9e1f2; text-align: center; padding: 5px;">Green Status</th> <th style="background-color: #d9e1f2; text-align: center; padding: 5px;">IEC 62474</th> </tr> </thead> <tbody> <tr> <td style="text-align: center; padding: 5px;"><input checked="" type="checkbox"/> No Change</td> <td style="text-align: center; padding: 5px;"><input checked="" type="checkbox"/> No Change</td> <td style="text-align: center; padding: 5px;"><input checked="" type="checkbox"/> No Change</td> <td style="text-align: center; padding: 5px;"><input checked="" type="checkbox"/> No Change</td> </tr> </tbody> </table>						RoHS	REACH	Green Status	IEC 62474	<input checked="" type="checkbox"/> No Change			
RoHS	REACH	Green Status	IEC 62474										
<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change										
<b>Changes to product identification resulting from this PCN:</b>													
None													
<b>Product Affected:</b>													
<input type="checkbox"/> SN1607039QPWPRQ1	<input type="checkbox"/> TPS92691QPWPRQ1	<input type="checkbox"/> TPS92692QPWPQ1	<input type="checkbox"/> TPS92692QPWPTQ1										
<input type="checkbox"/> TPS92691QPWPQ1	<input type="checkbox"/> TPS92691QPWPTQ1	<input type="checkbox"/> TPS92692QPWPRQ1											

**Automotive Qualification Summary**  
 (As per AEC-Q100 Rev. J and JEDEC Guidelines)  
 Approve Date 31-March-2024

**Product Attributes**

Attributes		Qual Device: <a href="#">TPS92691QPWPRQ1</a>	QBS Process Reference:		QBS Package Reference:		QBS Package Reference:		QBS Product Reference:	
			<a href="#">S0704038C0PLPR</a>		<a href="#">TPS61175QPWPRQ1</a>		<a href="#">SN2HA08CQPWPRQ1</a>		<a href="#">TPS92691QPWPRQ1</a>	
<b>Automotive Grade Level</b>		Grade 1	Grade 1		Grade 1		Grade 1		Grade 1	
<b>Operating Temp Range (C)</b>		-40 to 125	-40 to 125		-40 to 125		-40 to 125		-40 to 125	
<b>Product Function</b>		Power Management	Power Management		Power Management		Power Management		Power Management	
<b>Wafer Fab Supplier</b>		RFAB	RFAB		MH8		RFAB		RFAB	
<b>Assembly Site</b>		TAI	TAI		TAI		TAI		TAI	
<b>Package Group</b>		TSSOP	QFP		TSSOP		TSSOP		TSSOP	
<b>Package Designator</b>		PWP	PLP		PWP		PWP		PWP	
<b>Pin Count</b>		16	128		14		24		16	

QBS: Qual By Similarity

Qual Device [TPS92691QPWPRQ1](#) is qualified at MSL3 260C

**Qualification Results**

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Spec	Min Lot Qty	SS / Lot	Test Name	Condition	Duration	Qual Device: <a href="#">TPS92691QPWPRQ1</a>	QBS Process Reference: <a href="#">S0704038C0PLPR</a>	QBS Package Reference: <a href="#">TPS61175QPWPRQ1</a>	QBS Package Reference: <a href="#">SN2HA08CQPWPRQ1</a>	QBS Product Reference: <a href="#">TPS92691QPWPRQ1</a>
<b>Test Group A - Accelerated Environment Stress Tests</b>												
PC	A1	JEDEC J-STD-020 JESD22-A113	3	77	Preconditioning	MSL3 260C	-	1/AI/0	3/AI/0	3/AI/0	3/AI/0	1/AI/0
HAST	A2	JEDEC JESD22-A110	3	77	Biased HAST	130C/85%RH	96 Hours	1/77/0	3/231/0	-	3/231/0	1/77/0
AC/UHAST	A3	JEDEC JESD22-A102/JEDEC JESD22-A118	3	77	Autoclave	121C/15psig	96 Hours	-	3/231/0	-	3/231/0	1/77/0
AC/UHAST	A3	JEDEC JESD22-A102/JEDEC JESD22-A118	3	77	Unbiased HAST	130C/85%RH	96 Hours	1/77/0	-	3/231/0	-	-
TC	A4	JEDEC JESD22-A104 and Appendix 3	3	77	Temperature Cycle	-55C/150C	1000 Cycles	1/77/0	-	-	-	-
TC	A4	JEDEC JESD22-A104 and Appendix 3	3	77	Temperature Cycle	-65C/150C	500 Cycles	-	3/236/0	3/231/0	3/231/0	1/77/0
TC-BP	A4	MIL-STD883 Method 2011	1	5	Post Temp Cycle Bond Pull	-	-	-	1/5/0	1/5/0	-	1/5/0
PTC	A5	JEDEC JESD22-A105	1	45	PTC	-40/125C	1000 Cycles	-	3/45/0	-	1/45/0	-
HTSL	A6	JEDEC JESD22-A103	1	45	High Temperature Storage Life	150C	1000 Hours	1/45/0	-	1/45/0	3/135/0	-
HTSL	A6	JEDEC JESD22-A103	1	45	High Temperature Storage Life	175C	500 Hours	-	3/45/0	-	-	-
<b>Test Group B - Accelerated Lifetime Simulation Tests</b>												
HTOL	B1	JEDEC JESD22-A108	3	77	Life Test	125C	1000 Hours	-	3/231/0	-	-	-
HTOL	B1	JEDEC JESD22-A108	3	77	Life Test	150C	300 Hours	-	-	-	-	3/231/0

Type	#	Test Spec	Min Lot Qty	SS / Lot	Test Name	Condition	Duration	Qual Device: <a href="#">TPS92691QPWPRQ1</a>	QBS Process Reference: <a href="#">S0704038C0PLPR</a>	QBS Package Reference: <a href="#">TPS61175QPWPRQ1</a>	QBS Package Reference: <a href="#">SN2HA08CQPWPRQ1</a>	QBS Product Reference: <a href="#">TPS92691QPWPRQ1</a>
HTOL	B1	JEDEC JESD22-A108	3	77	Life Test	150C	408 Hours	-	-	-	3/231/0	-
ELFR	B2	AEC Q100-008	3	800	Early Life Failure Rate	125C	48 Hours	-	3/2400/0	-	-	-
ELFR	B2	AEC Q100-008	3	800	Early Life Failure Rate	150C	24 Hours	-	-	-	3/2400/0	-
EDR	B3	AEC Q100-005	1	77	NVM Endurance, Data Retention, and Op Life	Per QSS-009-018	1 Step	-	-	-	3/231/0	-
<b>Test Group C - Package Assembly Integrity Tests</b>												
WBS	C1	AEC Q100-001	1	30	Wire Bond Shear	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	1/30/0	-	3/90/0	3/90/0	1/30/0
WBP	C2	MIL-STD883 Method 2011	1	30	Wire Bond Pull	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	1/30/0	-	3/90/0	3/90/0	1/30/0
SD	C3	JEDEC J-STD-002	1	15	PB-Free Solderability	>95% Lead Coverage	-	-	-	-	1/15/0	1/15/0
PD	C4	JEDEC JESD22-B100 and B108	3	10	Physical Dimensions	Cpk>1.67	-	-	-	3/30/0	3/30/0	1/10/0
<b>Test Group D - Die Fabrication Reliability Tests</b>												
EM	D1	JESD61	-	-	Electromigration	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
TDDB	D2	JESD35	-	-	Time Dependent Dielectric Breakdown	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
HCI	D3	JESD60 & 28	-	-	Hot Carrier Injection	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
BTI	D4	-	-	-	Bias Temperature Instability	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
SM	D5	-	-	-	Stress Migration	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
<b>Test Group E - Electrical Verification Tests</b>												
ESD	E2	AEC Q100-002	1	3	ESD HBM	-	2000 Volts	-	1/3/0	-	3/9/0	1/3/0
ESD	E3	AEC Q100-011	1	3	ESD CDM	-	500 Volts	-	1/3/0	-	3/9/0	1/3/0
LU	E4	AEC Q100-004	1	6	Latch-Up	Per AEC Q100-004	-	-	1/6/0	-	1/6/0	1/3/0
ED	E5	AEC Q100-009	3	30	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	3/90/0	-	3/90/0	3/90/0

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

#### Ambient Operating Temperature by Automotive Grade Level:

Grade 0 (or E): -40C to +150C

Grade 1 (or Q): -40C to +125C

Grade 2 (or T): -40C to +105C

Grade 3 (or I) : -40C to +85C

#### E1 (TEST): Electrical test temperatures of Qual samples (High temperature according to Grade level):

Room/Hot/Cold : HTOL, ED

Room/Hot : THB / HAST, TC / PTC, HTSL, ELFR, ESD & LU

Room : AC/uHAST

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

**Automotive Qualification Summary**  
 (As per AEC-Q100, Q006 and JEDEC Guidelines)  
 Approve Date 31-March-2024

**Product Attributes**

Attributes		Qual Device: TPIC6C596PWRG4
Operating Temp Range		-40 to +125 C
Automotive Grade Level		Grade 1
Product Function		Logic
Wafer Fab Supplier		DFAB
Die Revision		B
Assembly Site		TAI
Package Type		TSSOP
Package Designator		PW
Ball/Lead Count		16

- QBS: Qual By Similarity
- Qual Device TPIC6C596PWRG4 is qualified at LEVEL1-260CG

**Qualification Results**

Data Displayed as: Number of lots / Total sample size / Total failed

	Type	#	Test Spec	Min Lot Qty	SS/ Lot	Test Name / Condition	Duration	Qual Device: TPIC6C596PWRG4
<b>Test Group A – Accelerated Environment Stress Tests</b>								
			AEC-Q006	-	-	Pre-Preconditioning SAM	-	Pass
	PC	A1	JEDEC J-STD-020 JESD22-A113	3	77	Automotive Preconditioning	Level 1-260C	Pass
			AEC-Q006	-	-	Post-Preconditioning SAM	-	Pass
	HAST	A2	JEDEC JESD22-A110	3	77	Biased HAST, 130C/85%RH	96 Hours	3/231/0
			AEC-Q006	3	22	HAST SAM	Post 96 Hours	3/66/0
	HAST	A2	JEDEC JESD22-A110	3	70	Biased HAST, 130C/85%RH	192 Hours	3/210/0
			AEC-Q006	3	22	HAST SAM	Post 192 Hours	3/66/0
	AC	A3	JEDEC JESD22-A102	3	77	Autoclave 121C	96 Hours	3/231/0
	AC	A3	JEDEC JESD22-A102	3	77	Autoclave 121C	192 Hours	3/231/0
	TC	A4	JEDEC JESD22-A104 and Appendix 3	3	77	Temperature Cycle, -65/150C	500 Cycles	3/231/0
			AEC-Q006	3	22	Temp Cycle SAM	Post 500 Cycles	3/66/0
			AEC-Q006	3	3	Temp Cycle Bond Pull (Ball Bond)	Post 500 Cycles	3/9/0

			AEC-Q006	3	3	Temp Cycle Bond Pull (Stitch Bond)	Post 500 Cycles	3/9/0
			AEC-Q006	3	3	Temp Cycle Bond Shear	Post 500 Cycles	3/9/0
			AEC-Q006	3	1	Temp Cycle Cross-Section	Post 500 Cycles	3/3/0
TC	A4	JEDEC JESD22-A104 and Appendix 3	3	70	Temperature Cycle, -65/150C	1000 Cycles		3/210/0
		AEC-Q006	3	22	Temp Cycle SAM	Post 1000 Cycles		3/66/0
		AEC-Q006	3	2	Temp Cycle Bond Pull (Ball Bond)	Post 1000 Cycles		3/6/0
		AEC-Q006	3	2	Temp Cycle Bond Pull (Stitch Bond)	Post 1000 Cycles		3/6/0
		AEC-Q006	3	2	Temp Cycle Bond Shear	Post 1000 Cycles		3/6/0
		AEC-Q006	3	1	Temp Cycle Cross-Section	Post 1000 Cycles		3/3/0
PTC	A5	JEDEC JESD22-A105	1	45	Power Temperature Cycle, -40/125C	1000 Cycles		1/45/0
PTC	A5	JEDEC JESD22-A105	1	45	Power Temperature Cycle, -40/125C	2000 Cycles		1/45/0
HTSL	A6	JEDEC JESD22-A103	3	45	High Temp. Storage Bake, 150C	1000 Hours		3/135/0
		AEC-Q006	3	1	HTSL Cross-Section	Post 1000 Hours		3/3/0
HTSL	A6	JEDEC JESD22-A103	3	45	High Temp. Storage Bake, 150C	2000 Hours		3/132/0
		AEC-Q006	3	1	HTSL Cross-Section	Post 2000 Hours		3/3/0
<b>Test Group B – Accelerated Lifetime Simulation Tests</b>								
	HTOL	B1	JEDEC JESD22-A108	3	77	Life Test, 125C	1000 Hours	3/231/0
	EDR	B3	AEC Q100-005	3	77	NVM Endurance, Data Retention, and Operational Life	--	N/A
<b>Test Group C – Package Assembly Integrity Tests</b>								
	WBS	C1	AEC Q100-001	1	30	Bond Shear (Cpk>1.67)	Wires	3/90/0
	WBP	C2	MIL-STD883 Method 2011	1	30	Bond Pull (Cpk>1.67)	Wires	3/90/0
	SD	C3	JEDEC JESD22-B102	1	15	Surface Mount Solderability	Pb	3/45/0
	SD	C3	JEDEC JESD22-B102	1	15	Surface Mount Solderability	Pb Free	3/45/0
	LI	C6	JEDEC JESD22-B105	1	50	Lead Fatigue	Leads	3/66/0
	LI	C6	JEDEC JESD22-B105	1	50	Lead Pull to Destruction	Leads	3/66/0
<b>Test Group E – Electrical Verification Tests</b>								

	ED	E5	AEC Q100-009	3	30	Auto Electrical Distributions	Cpk>1.67	3/90/0
<b>Additional Tests</b>								
	FLAM			-	-	Flammability (UL 94V-0)	Method A	3/15/0

A1 (PC): Preconditioning:

Performed for THB, Biased HAST, AC, uHAST & TC samples, as applicable.

Junction Operating Temperature by Automotive Grade Level:

Grade 0 (or E): -40°C to +150°C

Grade 1 (or Q): -40°C to +125°C

Grade 2 (or T): -40°C to +105°C

Grade 3 (or I) : -40°C to +85°C

E1 (TEST): Electrical test temperatures of Qual samples (High temperature according to Grade level):

Room/Hot/Cold : HTOL, ED

Room/Hot : THB / HAST, TC / PTC, HTSL, ELFR, ESD & LU

Room : AC/uHAST

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

ZVEI ID: SEM-PA-08

For questions regarding this notice, e-mails can be sent to Change Management team or your local Field Sales Representative.

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